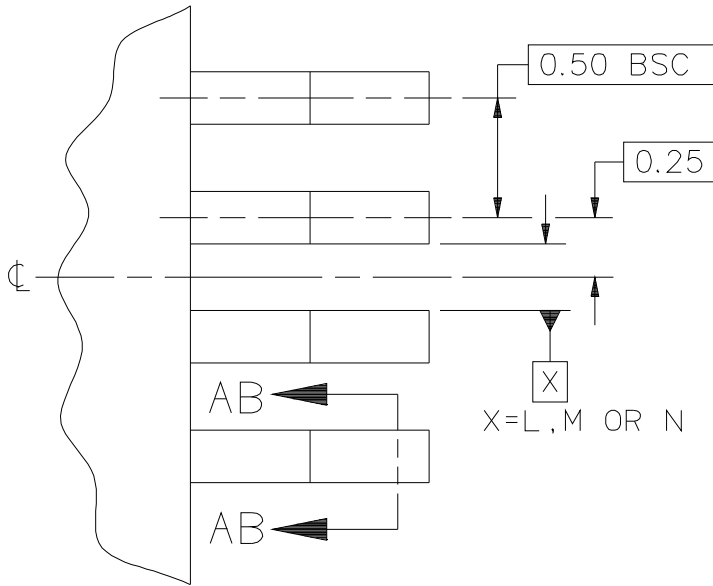
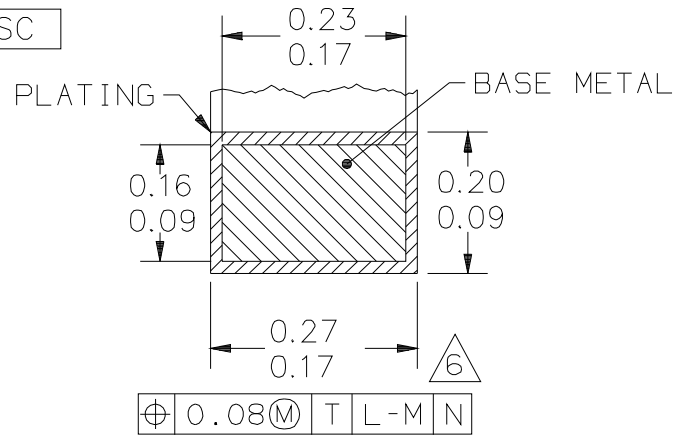


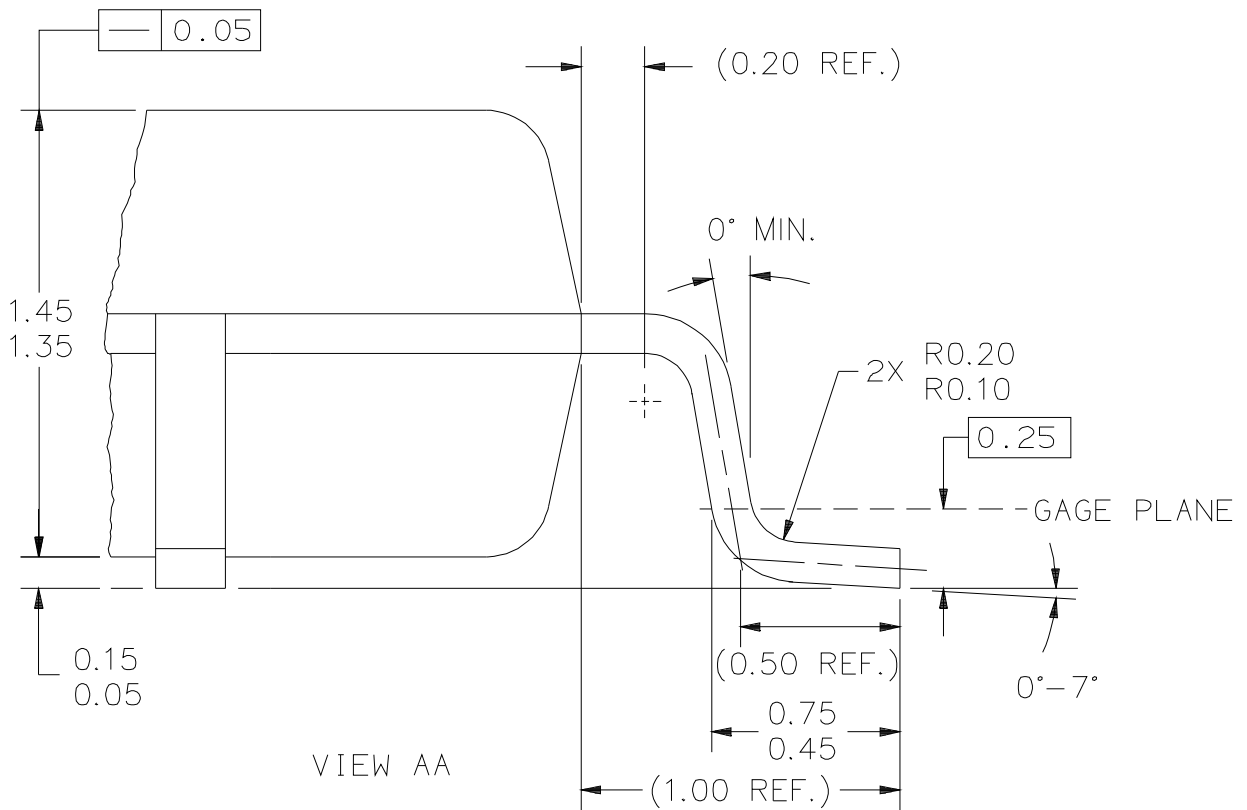
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TITLE: 208 LD TQFP, 28 X 28 PKG, 0.50 PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23458W	REV: E
	STANDARD: JEDEC MS-026 BJB	
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VIEW Y



SECTION AB-AB
ROTATED 90° CLOCKWISE
208 PLACES



VIEW AA

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	STANDARD: JEDEC MS-026 BJB	
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NOTES

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.
2. DIMENSIONS IN MILLIMETERS.
3. DATUMS L, M AND N TO BE DETERMINED AT THE SEATING PLANE, DATUM T.

4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE, DATUM T.

5. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS INCLUDE MOLD MISMATCH.

6. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD 0.07.

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